

V

mΩ

А

D

650

190

20

 $V_{DS}@T_{jmax}$

GC

R_{DS(ON)}

 I_D

N-Channel Super Junction Power MOSFET

General Description

The series of devices use advanced super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

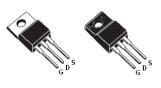
- •New technology for high voltage device
- •Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

Package Marking And Ordering Information

Device	Device Package	Marking
NCE20N60	TO-220	NCE20N60
NCE20N60F	TO-220F	NCE20N60F



Schematic diagram

TO-220 TO-220F

Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	NCE20N60	NCE20N60F	Unit
Drain-Source Voltage (VGs=0V)	Vds	6	00	V
Gate-Source Voltage (VDs=0V)	Vgs	±	30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	20	20*	А
Continuous Drain Current at Tc=100°C	I _{D (DC)}	12.5	12.5*	А
Pulsed drain current (Note 1)	DM (pluse)	60	60*	А
Drain Source voltage slope, VDS = 480 V, ID = 20 A, Tj =	dv/dt		50	V/ns
125 °C	uv/ut			V/115
Maximum Power Dissipation(Tc=25°C)	PD	208	34.5	W
Derate above 25°C		1.67	0.28	W/°C
Single pulse avalanche energy (Note 2)	Eas	6	90	mJ
Avalanche current ^(Note 1)	I _{AR}	2	20	А



Parameter	Symbol	NCE20N60	NCE20N60F	Unit
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	1	I	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55	+150	°C

* limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE20N60	NCE20N60F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.6	3.6	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	80	°C /W

Table 3. Electrical Characteristics (TA=25[°]C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states		·			•	
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	600			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =600V,V _{GS} =0V		0.05	1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±30V, V_{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2.5	3	3.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A		160	190	mΩ
Dynamic Characteristics						
Forward Transconductance	g fs	V _{DS} = 20V, I _D = 10A		17.5		S
Input Capacitance	C _{lss}			2400		PF
Output Capacitance	Coss	- V _{DS} =50V,V _{GS} =0V, - F=1.0MHz		180		PF
Reverse Transfer Capacitance	C _{rss}			5.7		PF
Total Gate Charge	Qg	\/ _400\/↓ _20A		55	114	nC
Gate-Source Charge	Q _{gs}	V _{DS} =480V,I _D =20A, V _{GS} =10V		11		nC
Gate-Drain Charge	Q _{gd}	VGS-10V		22		nC
Intrinsic gate resistance	R _G	f = 1 MHz open drain		0.9		Ω
Switching times						
Turn-on Delay Time	t _{d(on)}			10		nS
Turn-on Rise Time	t _r	V _{DD} =380V,I _D =20A,		5		nS
Turn-Off Delay Time	t _{d(off)}	R_G =3.6 Ω , V_{GS} =10V		67	100	nS
Turn-Off Fall Time	t _f			4	12	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T -25°0			20	А
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			60	А
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =20A,V _{GS} =0V		0.9	1.3	V
Reverse Recovery Time	trr			500		nS
Reverse Recovery Charge	Qrr	− Tj=25°C,I _F =20A,di/dt=100A/μs		11		uC
Peak Reverse Recovery Current	I _{rrm}			60		А

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

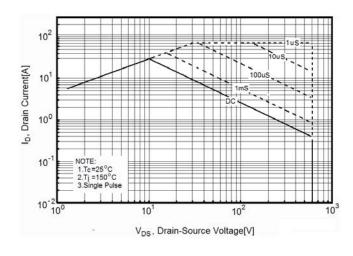


Figure1. Safe operating area for NCE20N60

Figure3. Source-Drain Diode Forward Voltage

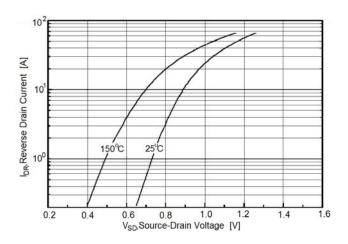


Figure5. Transfer characteristics

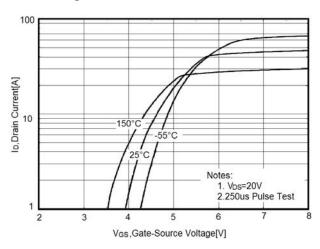


Figure2. Safe operating area for NCE20N60F

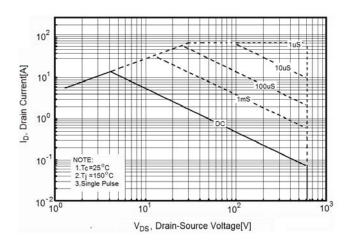


Figure4. Output characteristics

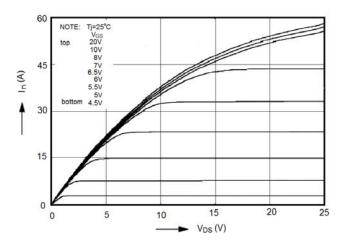
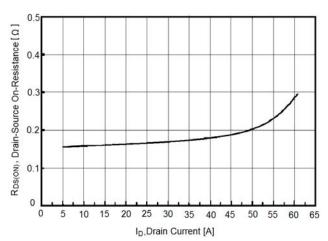


Figure6. Static drain-source on resistance





25

20

15

10

5

0

25

ID, Drain Current [A]

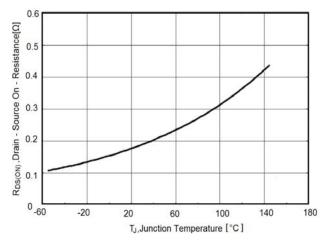


Figure9. Maximum I_D vs Junction Temperature

100

125

150

Figure7. R_{DS(ON)} vs Junction Temperature

Figure8. BV_{DSS} vs Junction Temperature

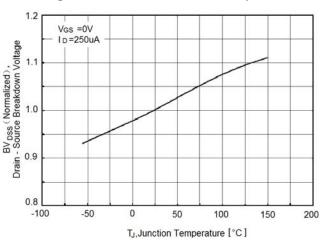


Figure10. Gate charge waveforms

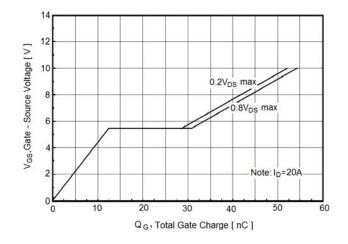


Figure11. Capacitance

75

Tc,Case Temperature[°C]

50

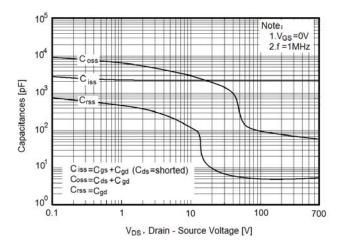


Figure12. Transient Thermal Impedance for NCE20N60

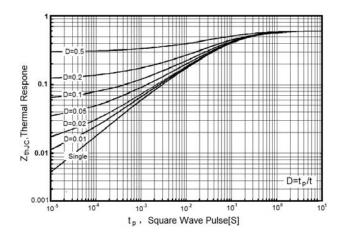
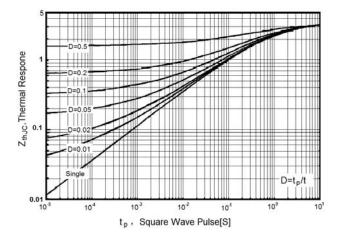




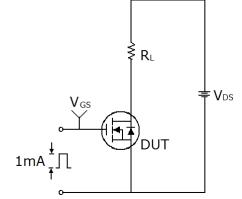
Figure13. Transient Thermal Impedance for NCE20N60F



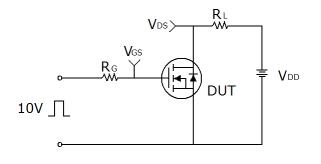


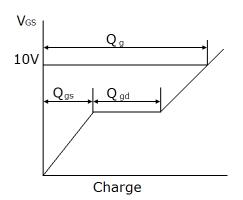
Test circuit

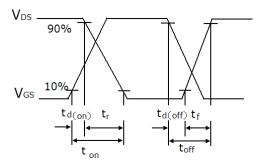
1) Gate charge test circuit & Waveform



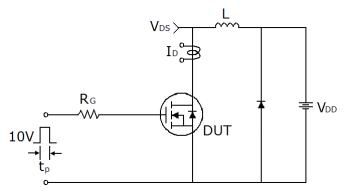
2) Switch Time Test Circuit:

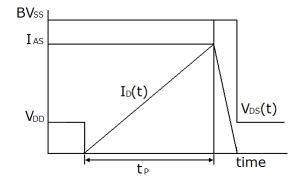






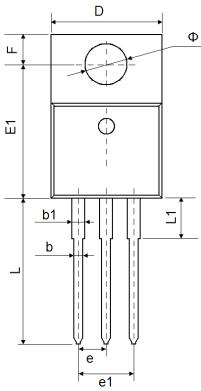
3) Unclamped Inductive Switching Test Circuit & Waveforms

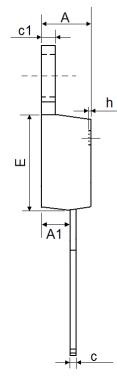


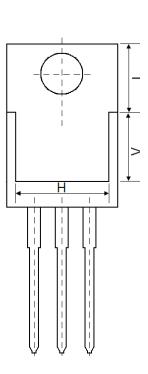




TO-220-3L Package Information



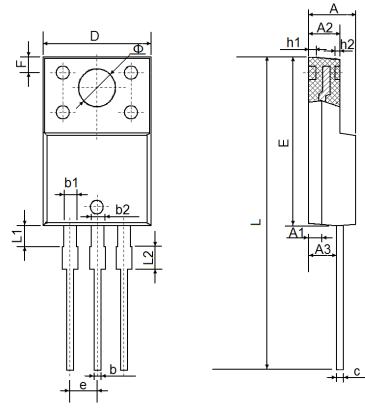




Symbol	Dimension	s In Millimeters	Dimensions In Inches	
	Min.	Max.	Min.	Max.
А	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	10.010	10.350	0.394	0.407
E	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
е	2.5	40 TYP.	0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
Н	8.4	40 REF.	0.332 REF.	
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
V	6.060 REF.		0.239	REF.
I	6.600 REF.		0.260	REF.
Φ	3.735	3.935	0.147	0.155



TO-220F Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.300	4.700	0.169	0.185	
A1	1.30	0REF	0.051	REF	
A2	2.800	3.200	0.110	0.126	
A3	2.500	2.900	0.098	0.114	
b	0.500	0.750	0.020	0.030	
b1	1.100	1.350	0.043	0.053	
b2	1.500	1.750	0.059	0.069	
С	0.500	0.750	0.020	0.030	
D	9.960	10.360	0.392	0.408	
E	14.800	15.200	0.583	0.598	
е	2.54	OTYP.	0.100TYP		
F	2.70	0REF	0.106REF		
Φ	3.50	0REF	0.138REF		
h1	0.800REF		0.031REF		
h2	0.500REF		0.020REF		
L	28.000	28.400	1.102	1.118	
L1	1.700	1.900	0.067	0.075	
L2	1.900	2.100	0.075	0.083	



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